Product Preview

Schottky Barrier Diode

These Schottky barrier diodes are optimized for low forward voltage drop and low leakage current.

Features

- Very Low Forward Voltage Drop 350 mV @ 1 mA
- Low Reverse Current 0.2 μA @ 10 V
- 100 mA of Continuous Forward Current
- ESD Rating Human Body Model: Class 3B
 - Machine Model: Class C
- This is a Halide-Free Device
- This is a Pb-Free Device

Typical Applications

- LCD and Keypad Backlighting
- Camera Photo Flash
- Buck and Boost dc-dc Converters
- Reverse Voltage and Current Protection
- Clamping & Protection

Markets

- Mobile Handsets
- MP3 Players
- Digital Camera and Camcorders
- Notebook PCs & PDAs
- GPS

MAXIMUM RATINGS

Rating		Symbol	Value	Unit
Reverse Voltage		V _R	30	V
Forward Current (DC)		IF	100	mA
Forward Surge Current (60 Hz @ 1 cycle)		I _{FSM}	2.0	Α
ESD Rating:	Human Body Model Machine Model	ESD	>8.0 >400	kV V

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

This document contains information on a product under development. ON Semiconductor reserves the right to change or discontinue this product without notice.

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30 V SCHOTTKY **BARRIER DIODE**





X3DFN2 CASE 152AF



PIN 1 EM

Ε = Specific Device Code М

= Date Code

ORDERING INFORMATION

Device	Package	Shipping†		
NSR01L30MUT5G	X3DFN2 (Pb-Free)	15000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Min	Тур	Max	Unit
Thermal Resistance Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C				695 180	°C/W mW
Storage Temperature Range	T _{stg}			-55 to +150	°C
Junction Temperature	TJ			+150	°C

^{1.} Mounted onto a 4 in square FR-4 board 100 mm sq. 2 oz. Cu 0.06" thick single-sided. Operating to steady state.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Leakage (V _R = 10 V) (V _R = 30 V)	I _R			0.2 0.5	μΑ
Forward Voltage (I _F = 1 mA) (I _F = 10 mA)	V _F			0.35 0.46	V
Total Capacitance (V _R = 5.0 V, f = 1 MHz)	СТ		0.8		pF

TYPICAL CHARACTERISTICS

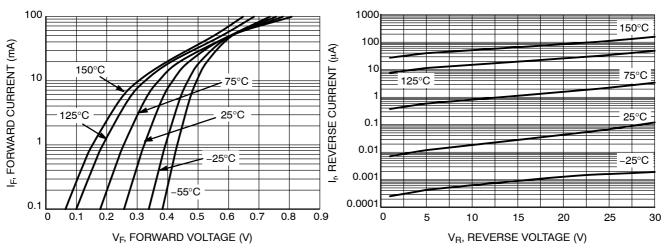


Figure 1. Forward Voltage

Figure 2. Leakage Current

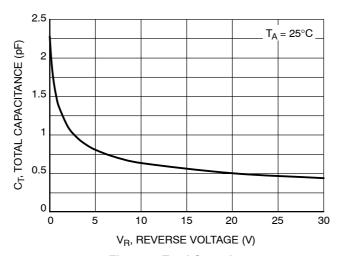
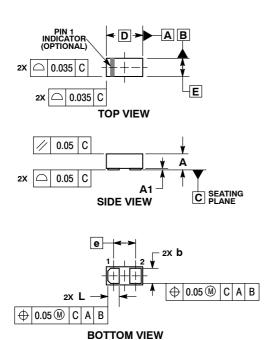


Figure 3. Total Capacitance

PACKAGE DIMENSIONS

X3DFN2, 0.62x0.32, 0.355P, (0201) CASE 152AF-01 ISSUE O

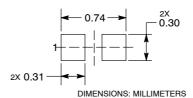


NOTES

- DIMENSIONING AND TOLERANCING PER
 ASME Y14 5M 1994
- 2. CONTROLLING DIMENSION: MILLIMETERS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.25	0.33		
A 1		0.05		
b	0.22	0.28		
D	0.62	BSC		
Е	0.32 BSC 0.355 BSC			
e				
L	0.17	0.23		

RECOMMENDED MOUNTING FOOTPRINT*



See Application Note AND8398/D for more mounting details

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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